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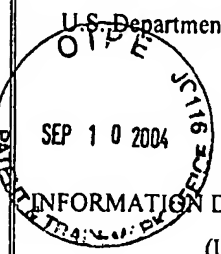
Application No.:	10/090,316
Filing Date:	March 1, 2002
First Named Inventor:	Peter G. Borden
Group Art Unit:	2877
Examiner Name:	Rosenberger, Richard A.
Confirmation No.:	5495
Attorney Docket No.:	BOX006 US

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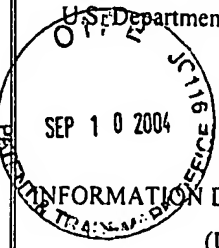
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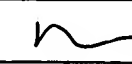


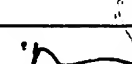
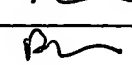
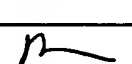
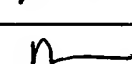
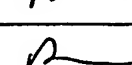

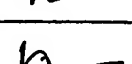

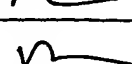
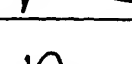

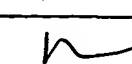
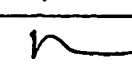
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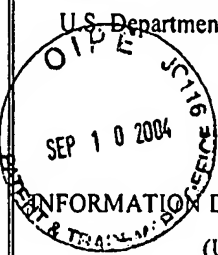
U.S. Patent Documents								
*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate	
<i>m</i>	95.	4,679,946	7/14/87	Rosencwaig et al.	374	5		
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
<i>JRM</i>	96.	J. Opsal, "High Resolution Thermal Wave Measurements and Imaging of Defects and Damage in Electronic Materials" Photoacoustic and Photothermal Phenomena II, Springer Series in Optical Sciences, Vol. 62, Springer Verlag Berlin, Heidelberg, 1990.						
<i>RAL</i>	97.	A. Rosencwaig, "Thermal Wave Measurement of Thin-Film Thickness", 1986 American Chemical Society, pp.182-191						
<i>RA</i>	98.	A. Rosencwaig et al., "Thin-Film Thickness Measurements with Thermal Waves", Journal De Physique, October 1983, pp. C6-483 - C6-489						
<i>m</i>	99.	W. L. Smith et al. "Thermal-wave Measurements and Monitoring of TaSi _x Silicide Film Properties" J. Vac. Technol. B2(4), Oct.-Dec. 1984, pp. 710-713						
<i>m</i>	100.	A. Salnick et al., "Nonlinear Fundamental Photothermal Response in 3D Geometry: Experimental Results for Tungsten", (believed to be prior to March 1, 2002)						
<i>m</i>	101.	S. Ameri et al., "Photo-Displacement Imaging", March 30, 1981, pp. 337-338						
<i>m</i>	102.	L. Chen et al., "Thermal Wave Studies of Thin Metal Films Using the Meta-Probe-A New Generation Photothermal System" 25th Review of Progress in QNDE, Snowbird, UT 19-24 July, 1998, pp 1-12						
<i>m</i>	103.	P. Alpern and S. Wurm, "Modulated Optical Reflectance Measurements on Bulk Metals and Thin Metallic Layers", J. Appl. Phys. 66(4), 15 August 1989, pp 1676-1679						
<i>m</i>	104.	J. Opsal, "The Application of Thermal Wave Technology to Thickness and Grain Size Monitoring of Aluminum Films", SPIE Vol. 1596 Metalization Performance and Reliability Issues for VLSI and ULSI (1991), pp 120-131						
<i>m</i>	105.	A. Rosencwaig, "Process Control In IC Manufacturing With Thermal Waves", Review of Progress in Quantitative Nondestructive Evaluation, Vol.9, 1990, pp 2031-2037						
<i>m</i>	106.	K. Farnaam, "Measurement of Aluminum Alloy Grain Size on Product Wafers and its Correlation to Device Reliability", 1990 WLR Final Report, pp 97-106						
<i>R</i>	107.	B.C. Forget et al., "High Resolution AC Temperature Field Imaging", Electronic Letters 25th September 1997, Vol. 33 No. 20, pp 1688-1689						


Examiner: <i>RA Rosenberger</i>	Date Considered: <i>11/24/04</i>
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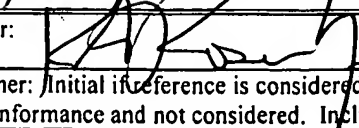
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	109.	C. Paddock et al., "Transient Thermoreflectance from Metal Films", J. Appl. Phys. 60(1), 1 July 1986, pp 285-290
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	116.	W. Lee Smith, "Direct Measurement of Stress-Induced Void Growth by Thermal Wave Modulated Optical Reflectance Imaging", 1991 IEEE/IRPS, pp 200-208
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	121.	L. Chen et al., "Meta-Probe: A New Generation Photothermal System For Thin Metal Films Characterization" (believed to be prior to March 1, 2002)
	122.	L. Chen et al., "Thermal Wave Studies of Thin Metal Films and Structures", (believed to be prior to March 1, 2002)
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